

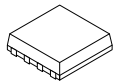
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

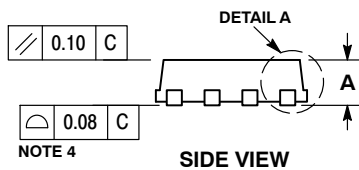
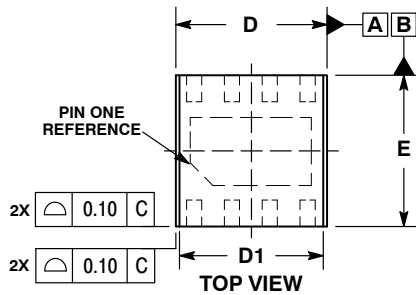


CUDFN8, 2x2, 0.5P
CASE 505AF-01
ISSUE 0

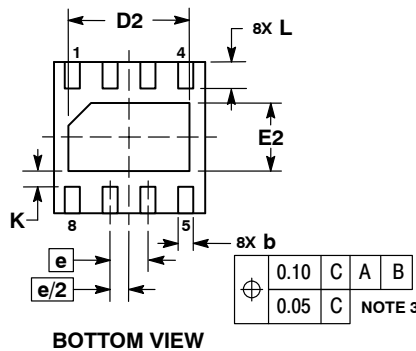
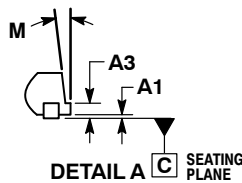
DATE 20 JAN 2011



SCALE 4:1



END VIEW

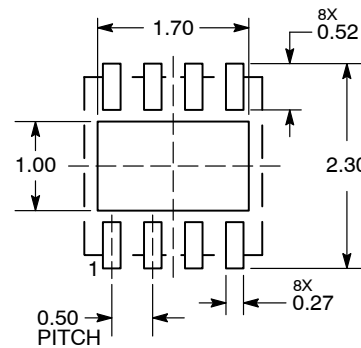


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.55	0.65
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
D	2.00 BSC	
D1	1.80 BSC	
D2	1.50	1.70
E	2.00 BSC	
E2	0.80	1.00
e	0.50 BSC	
K	0.20	---
L	0.25	0.35
M	---	10°

RECOMMENDED
MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	CUDFN8 2X2, 0.5P	PAGE 1 OF 2

